Conductive Microstructures and Connections for Microelectronics Made by Ink-Jet Technology

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Materials with nano size fillers create very new possibilities and new applications.

New possibilities needs special type of equipment.

**Equipment -> Ink Jet Dispenser System.**

Short reminder for Ink Jet possibilities and requirements:

- **Single drop volume:** 30 – 500 picoliters with variation approx. 1%
- **Droplet diameter:** 30 – 100 µm
- **Drop rate:** 0 – 2000/sec.
- **Fluid viscosity range:** 0.5 ~ 30 mPas. (unheated)
- **Drop acceleration:** $10^5 g$ (during each shoot)
Ink Jet technology is well known for many applications especially when very uniform fluid is used.

With formulations which is mixture of two different phases: fluid binder and solid filler – problem is much more complicated. Let’s use some fluid classification:

• Mechanical type – classical, when filler over $0.5\mu m$ is used.
• Colloidal type – when filler is in range $0.5\mu m \sim 50\text{ nm}$.
• True fluid type (similar “molecular” type) – when filler is less 20 nm.
Both: mechanical and colloidal types need very special ingredients and technology, but always the major problem will be exist - sedimentation.

Very low binder viscosity plus:
- filler has much higher specific gravity,
- filler has much bigger particle size than binder molecule size,
- high % of filler inside formula
Much better situation is when conductive filler has diameter less 10 nm. Than formulation start to be very uniform and stable with properties similar to "true fluid".

Is a number methods for obtaining nano size silver powder, for example:

- Metal dissipation in plasma process,
- Chemical reaction process,
- Electrochemical process,
- Thermal decomposition process,
- Vapor condensation process, etc.
For preparing silver with size of single nano range, thermal decomposition of silver salts were used.

During very accurate studies this technology phenomena, Amepox established own process conditions and we are working with.
SEM Pictures of Nano Silver Agglomerates

Courtesy Solid State Physics University of Łódź.
STM Pictures of Nano Silver

Courtesy Solid State Physics University of Łódź.
Histogram for particles size of Amepeox

Silver particle dimension [nm]

Number of particles [%]

Silver Atom Diameter 2.88 Å \( (1 \text{ nm} = 10 \text{ Å}) \)

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# Electrically Conductive Ink with Nano Silver

<table>
<thead>
<tr>
<th><strong>Number of components</strong></th>
<th><strong>One</strong></th>
</tr>
</thead>
<tbody>
<tr>
<td><strong>Consistency</strong></td>
<td>Very low viscous ink</td>
</tr>
<tr>
<td><strong>Color</strong></td>
<td>Dark brown to black with metallic shade</td>
</tr>
<tr>
<td><strong>Percentage of silver filler (inside ink)</strong></td>
<td>40 – 60 % <em>(actual 45%)</em></td>
</tr>
<tr>
<td><strong>Specific gravity</strong></td>
<td>1.3 – 1.6 g/cm³</td>
</tr>
<tr>
<td><strong>Viscosity</strong></td>
<td>1.4 – 1.55 mPas</td>
</tr>
<tr>
<td><strong>Thixotropy index</strong></td>
<td>~ 1.0</td>
</tr>
<tr>
<td><strong>Surface tension value</strong></td>
<td>28.5 – 32.5 dynes/cm</td>
</tr>
<tr>
<td><strong>Recommended sintering conditions</strong></td>
<td>230 °C - 60 min</td>
</tr>
<tr>
<td><strong>Percentage of silver after „curing”</strong></td>
<td>95 – 97 %</td>
</tr>
<tr>
<td><strong>Electrical resistivity</strong></td>
<td><em>(1 – 3 )</em> 10⁻⁵ Ωcm</td>
</tr>
<tr>
<td><strong>Storage</strong></td>
<td>6 months in room temperature</td>
</tr>
</tbody>
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Results of Ink Jet tests

Dots: Macro Picture

Nozzle 66 microns

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Results of Ink Jet tests

Nozzle 66 microns

Mag. X 200

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Results of Ink Jet tests

Lines: **Nozzle 66 microns**

Single line SEM picture

Macro Picture

Courtesy of TNO Industrial-Eindhoven

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Obtaining electrical conductivity

Each nAg particle is protected by special chemical „schell“. This „schell” layer is built during nAg production process.

Ag 95.3 %
C 2.7±1.0 %
Tolerance ± 1 %
Obtaining electrical conductivity as a function of sintering time

- Resistivity [Ohm cm] \times 10^{-5}
- Sintering temperature [°C]: 150, 175, 200, 235
- Sintering time [min]: 1h, 5h, 9h

Slintering temp. 235°C
Obtaining electrical conductivity - Phenomena -

For electrical conductivity - is necessary to remove protection chemical "schell"

Purity test by EDX method:

LEFT – Just after drying

RIGHT – after sintering 175°C/9 h

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Obtaining electrical conductivity

-Sintering Phenomena-

175°C – 9 h

230°C – 1 h

200°C – 9 h

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CONCLUSIONS:

1. Nature of nAg powder needs protective „schell” with chemical depended from technology.
2. Mechanism obtaining electrical conductivity is different like for standard (micron size Ag) Inks.
3. The major role in this mechanism plays kind of „schell” and it’s removing from nAg surface and nAg sintering.

ADVANTAGES:

5. Very high packaging possibility,
6. Nature of Nano Inks - formula is with the best homogeneous properties (uniform concentration),
7. The highest repeatability of dosing ink volumes,
8. Very high repeatability of printed shapes,